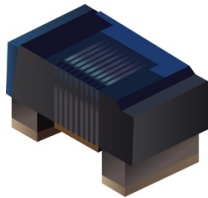


# MATERIAL DECLARATION SHEET



Material Number	CWF2012A Series			
Product Line	Chip Inductor			
Compliance Date	2023/10/11			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ferrite body	Ferrite Ni-Zn Series	0.00912	Iron oxide	1309-37-1	62.000	47.120	76.00
				Nickel oxide	1313-99-1	11.000	8.360	
				Zinc oxide	1314-13-2	20.000	15.200	
				Copper oxide	1317-38-0	7.000	5.320	
2	Copper/ Coating	Copper Wire	0.00174048	Copper	7440-50-8	100.000	14.504	15.00
		ELEKTRISOLA POLYURETHANE-BASED INSULATION VARNISH_P180	0.00005952	Polyurethane Resin	26680-22-8	100.000	0.496	
3	Terminal	Silver paste_DP4303W	0.00036	Silver	7440-22-4	73.700	2.211	3.00
				Silicon dioxide	60676-86-0	15.800	0.474	
				Resins	9004-57-3	10.500	0.315	
4	Solder Base	S Nickel Pellets	0.00012	Nickel	7440-02-0	100.000	1.000	1.00
5	Solder	Lead Free Solder	0.00012	Tin	7440-31-5	100.000	1.000	1.00
6	Back Membrane	UV Adhesive	0.00048	TRIPROPYLENE GLYCOL DIACRYLATE	42978-66-5	95.000	3.800	4.00
				HYDROXY CYCLOHEXYL PHENYL KETONE	947-19-3	5.000	0.200	
Total weight			0.012					

**This Document was updated on: 2023/10/11**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.